Docket No. 85A 3501 Date: February 5, 2004

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Dear Sir:

Transmitted herewith for filing is the patent application for inventor(s):

YOSHIYUKI OGATA and HISASHI ARAI

For: DIE E

DIE BONDING METHOD AND APPARATUS

Also enclosed are:

- Certified copy of Japanese Patent Application No. 2003-029183 of February 6, 2003 on which Convention priority is claimed
- Declaration and Power of Attorney
- ☐ Information Disclosure Statement by Applicant
- An assignment of the invention to <u>KABUSHIKI KAISHA SHINKAWA</u>

Applicant claims Small Entity Status

		C	ALCULAT	ION OF FEES						
ITEM		TOTAL NO. OF CLAIMS		NO. OF CLAIMS OVER BASE	LG/SM \$ ENTITY FEE		\$ AMOUNT		\$ FEE	
Α	TOTAL CLAIMS FEE	4	-20	0	LG=\$18 SM=\$9	\$18	\$	0		
В	INDEPENDENT CLAIMS FEE*	2	-3	0	LG=\$86 SM=\$43	\$86	\$	0		
С	SUBTOTAL - ADDITIONAL CLAIMS FEE (ADD FINAL COLUMN IN LINES A + B)								\$	0
D	MULTIPLE-DEPENDENT CLAIMS FEE  LARGE ENTITY FEE = \$25 SMALL ENTITY FEE = \$12							\$	0	
E	BASIC FEE  LARGE ENTITY FEE = \$77 SMALL ENTITY FEE = \$38							\$	385	
F	TOTAL FILING FEE (ADD TOTALS FOR LINES C, D, AND E)								\$	385
G	ASSIGNMENT RECORDING FEE						-	\$ 40	\$	40
	*LIST INDEPENDENT CLAIMS 1,	4								

- The Commissioner is hereby authorized to charge any additional fees which may be required, or credit any overpayment to Account No. 11-1445. A duplicate copy of this sheet is enclosed.
- A check in the amount of \$\(\frac{385}{}\) to cover the filing fee is enclosed.
- A check in the amount of \$\(\frac{40}{}\) to cover Assignment Recordation fee is enclosed.

Respectfully submitted, KODA & ANDROLIA

2029 Century Park East Suite 1430 Los Angeles, CA 90067-3024 (310) 277-1391 (310) 277-4118 -fax

Reg. No. 27,729

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail No. EV415842357US addressed to:

Mail Stop: Patent Application Commissioner for Patents PO Box 1450 Alexandria, VA 22313-1450

on February 5, 2004 by Inja Yi.

Dated:  $\frac{2}{2}$ 

D.,,

85A 3501

SHINKAWA

Applicant(s):

YOSHIYUKI OGATA and HISASHI ARAI

For:

DIE BONDING METHOD AND APPARATUS